

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

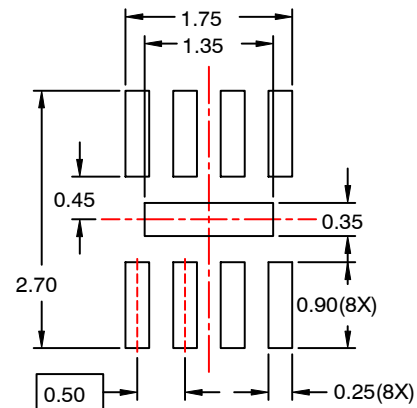
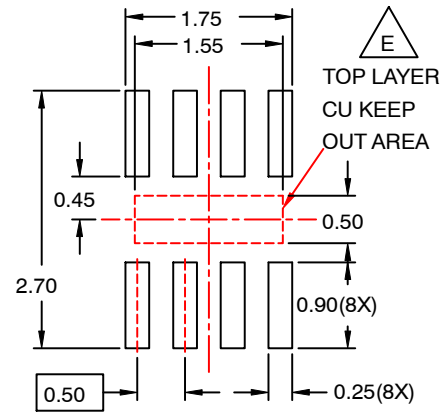
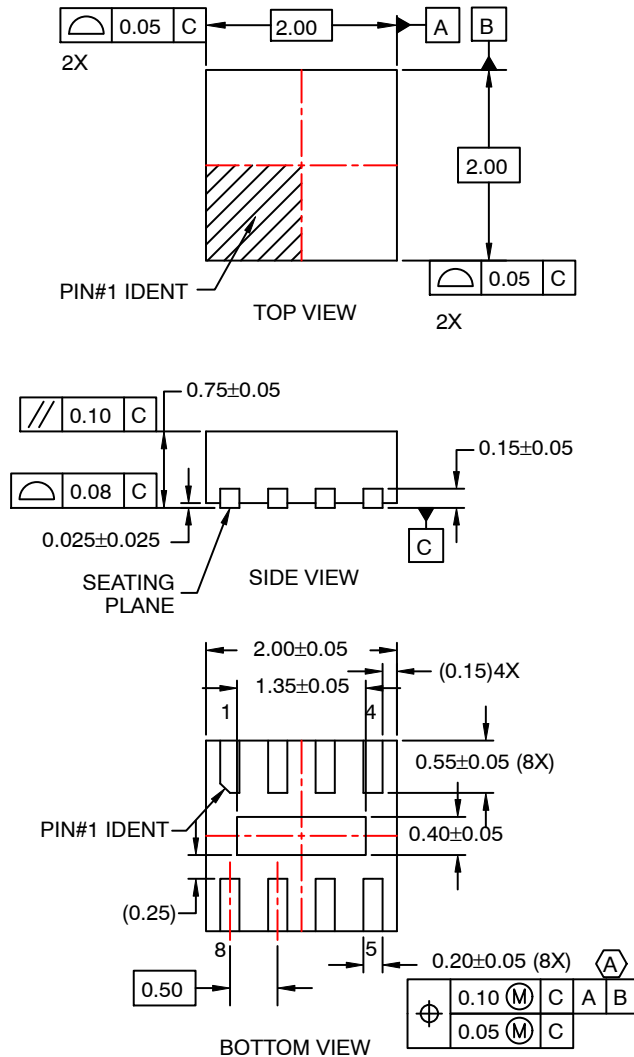
ON Semiconductor®



WDFN8 2x2, 0.5P

CASE 511DL
ISSUE O

DATE 31 JUL 2016



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)

NOTES:

- A PACKAGE CONFORMS TO JEDEC MO-229, VARIATION WCCE EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E IF CENTER PAD IS NOT SOLDERED TO, NO EXPOSED METAL IS ALLOWED IN THE TOP LAYER OF THE BOARD IN THE AREA SHOWN.

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